

between 0.5 and 5 micrometers.

31. (New) The microelectronic device according to claim 25, wherein the fiber reinforced encapsulation material includes a polymeric resin selected from epoxy and plastic.

### REMARKS

Applicant respectfully asserts that the claims are now in condition for examination. No new matter was added by the presentation of new claims 25-31. Support for new claim 25 comes from page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 26 comes from page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 27 comes from page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 28 comes from page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 29 comes from page 6, line 10 *et seq.*, page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 30 comes from page 6, line 10 *et seq.*, page 10, line 14 *et seq.*, FIG. 11, and throughout the specification. Support for new claim 31 comes from pages 3-6, and throughout the specification.

The Examiner is invited to contact Applicant's Representative John Greaves at 801/278-9171 or the below signed attorney if there are any questions regarding this Response or if prosecution of this application may be assisted thereby.

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Title: POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT  
PACKAGING

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this 25 day of October, 2002.

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Signature